2019 IEEE International Conference on
Smart Manufacturing, Industrial & Logistics Engineering (SMILE2019)
& 2019 International Symposium on Semiconductor Manufacturing Intelligence (ISMI2019)

April 19-21, 2019, Zhejiang University, Hangzhou, China
Conference Honorary Chair: Professor Andrew Kusiak, University of Iowa Informatics Initiative
Conference Chair: Professor Chen-Fu Chien, Taiwan Tsing Hua University

(http://smile.ieeng.org/)
The accepted full papers will be indexed by EI Compendex.

Aims and Topics:
The joint conference of 2019 IEEE International Conference on Smart Manufacturing, Industrial & Logistics Engineering (SMILE2019) and 2019 International Symposium on Semiconductor Manufacturing Intelligence (ISMI2019) aims to disseminate recent theoretical and methodological developments, applications, and case studies in light of ongoing revolutions for manufacturing intelligence and smart manufacturing including, yet not limited, the following topics:

**Keynote Speakers**
Professor Andrew Kusiak, the University of Iowa, USA, Editor-in-chief of Journal of Intelligent Manufacturing
Professor Tae-Eog Lee, Korea Advanced Institute of Science and Technology (KAIST), South Korea,
President of Korea Institute of Industrial Engineers (KIIE)
Professor Hing Kai Chan, Ningbo Nottingham University, China, Co-editor of Industrial Management & Data Systems
Professor Lihui Wang, KTH Royal Institute of Technology, Stockholm, Sweden,
Editor-in-Chief of Robotic and Computer-Integrated Manufacturing

**Submission:**
All papers must be written in English with a maximum length of 5 pages. For paper format, submission, and related information, please visit: http://smile.ieeng.org/ and submission page: https://easychair.org/conferences/?conf=smile2019.
For the accepted papers, please download Copyright in conference website by yourself, and send back to email: smile_ismi2019@163.com. The Full papers are reviewed for presentation at the conference as well as for publication in the conference proceedings which is indexed by EI. Extended version of some selected papers will be published in the SCI journals. Candidates are: Computers & Industrial Engineering, Journal of Intelligent Manufacturing, and International Journal of Industrial Engineering: TAP and so on.

**Important Dates:**
Deadline for submission of abstract/ special session proposals: December 1, 2018
Deadline for Full Paper Submission for EI indexed proceedings for IEEE Xplore: December 31, 2018—Extending to January 20, 2019
Deadline for Full Paper/Extended Abstract Submission: January 31, 2019
Camera Ready Manuscript Submission: February 28, 2019

**Contact:**
Ms Liu, conference secretary office, smile_ismi2019@163.com
Chia-Yu Hsu, Taipei University of Technology, chiayuhsu@mail.ntut.edu